

## S1L50000 SERIES HIGH DENSITY GATE ARRAY

### ■ DESCRIPTION

EPSON Electronics America, Inc.'s S1L50000 Series is a family of ultra high-speed VLSI CMOS gate array utilizing a 0.35µm "sea-of-gates" architecture. The S1L50000H products feature 5V tolerant I/O buffers.

- Ultra-high-speed, high density and low power consumption
- Low voltage operation: 3.3V and 2.0V
- Number of raw gates: 28,710 ~ 815,468 gates

### ■ FEATURES

- Process 0.35µm 2/3/4 layer metalization CMOS process
- Integration A maximum of 815,468 gates (2 input NAND gate equivalent)
- Operating Speed Internal gates: 140 ps (3.3V Typ), 210 ps (2.0V Typ)  
(2-input pair NAND, F/O = 2, Typical wire load)  
Input buffer: 380 ps (5.0V Typ) Built-in level shifter is used.  
400 ps (3.3V Typ), 1.30 ns (2.0V Typ)  
(F/O = 2, Typical wire load)  
Output buffer: 2.12 ns (5.0V Typ) Built-in level shifter is used.  
2.02 ns (3.3 V Typ), 3.90 ns (2.0V Typ)  
(C<sub>L</sub> = 15 pF)
- I/F Levels Input/Output TTL/CMOS/LVTTL compatible
- Input Modes TTL, CMOS, LVTTL, TTL Schmitt, CMOS Schmitt, LVTTL Schmitt, PCI  
Built-in pull-up and pull-down resistors can be usable.  
(2 types for each resistor value)
- Output Modes Normal, 3-state, bi-directional, PCI
- Output Drive I<sub>OL</sub> = 0.1, 1, 3, 8, 12, 24 mA selectable  
(Built-in level shifter is used at 5.0V)  
I<sub>OL</sub> = 0.1, 1, 2, 6, 12 mA selectable (at 3.3V)  
I<sub>OL</sub> = 0.05, 0.3, 0.6, 2, 4 mA selectable (at 2.0V)
- RAM Asynchronous 1-port, asynchronous 2-port
- Dual Power Operation supported by using level-shifter circuit  
Internal logic: Operation supported by low voltage  
I/O Buffer: Built-in interfaces of both high and low voltages possible
- Operation possible at V<sub>DD</sub> = 2.0 ± 0.2V

■ **LINE UP**

The S1L50000 Series comprises 11 types of masters, from which the customer is able to select the master most suitable.

Master	Total BC (Raw Gates)	Number of Pads	Number of Columns (X)	Number of Rows (Y)	Cell Utilization Ratio (U) <sup>*1</sup>		
					2-layer metal	3-layer metal	4-layer metal
S1L50282/283/284	28710	88	319	90	50%	88%	95%
S1L50752/753/754	75774	144	519	146	47%	85%	95%
S1L50992/993/994	99198	168	594	167	47%	85%	95%
S1L51252/253/254	125772	188	669	188	45%	80%	95%
S1L51772/773/774	177062	224	794	223	45%	75%	95%
S1L52502/503/504	250160	264	944	265	45%	75%	95%
S1L53352/353/354	335858	308	1094	307	43%	75%	95%
S1L54422/423/424	442112	352	1256	352	40%	70%	90%
S1L55062/063/064	506688	376	1344	377	40%	70%	90%
S1L56682/683/684	668552	432	1544	433	40%	70%	90%
S1L58152/153/154	815468	480	1706	478	40%	70%	90%

NOTE: \*1: This is the value when there are no cells, such as RAM cells. The cell use efficiency is dependent not only on the scope of the circuits, but also on the number of signals, the number of branches per signal, etc.; thus, use the values in this table only as an estimate

## ■ ELECTRICAL CHARACTERISTICS AND SPECIFICATIONS

### Absolute Maximum Ratings (For Single Power Supply):

(V<sub>SS</sub> = 0V)

Item	Symbol	Limits	Unit
Power Supply Voltage	V <sub>DD</sub>	-0.3 to 4.0	V
Input Voltage	V <sub>I</sub>	-0.3 to V <sub>DD</sub> + 0.5 <sup>*1</sup>	V
Output Voltage	V <sub>O</sub>	-0.3 to V <sub>DD</sub> + 0.5 <sup>*1</sup>	V
Output Current/Pin	I <sub>OUT</sub>	± 30	mA
Storage Temperature	T <sub>STG</sub>	-65 to 150	°C

1: Possible to use from -0.3V to 7.5V of I/O buffer voltage in the open-drain systems and input buffer in the IDC and IDH systems.

### Absolute Maximum Ratings (For Dual Power Supplies):

(V<sub>SS</sub> = 0V)

Item	Symbol	Limits	Unit
Power Supply Voltage	HV <sub>DD</sub>	-0.3 to 7.0	V
	LV <sub>DD</sub>	-0.3 to 4.0	V
Input Voltage	HV <sub>I</sub>	-0.3 to HV <sub>DD</sub> + 0.5 <sup>*1</sup>	V
	LV <sub>I</sub>	-0.3 to LV <sub>DD</sub> + 0.5 <sup>*1</sup>	V
Output Voltage	HV <sub>O</sub>	-0.3 to HV <sub>DD</sub> + 0.5 <sup>*1</sup>	V
	LV <sub>O</sub>	-0.3 to LV <sub>DD</sub> + 0.5 <sup>*1</sup>	V
Output Current/Pin	I <sub>OUT</sub>	± 30 (± 50 <sup>*2</sup> )	mA
Storage Temperature	T <sub>STG</sub>	-65 to 150	°C

1: Possible to use from -0.3V to 7.5V of I/O buffer voltage in the open-drain systems and input buffer in the IDC and IDH systems.

\*2: Possible to use for 24mA of output buffer.

**Recommended Operating Conditions (For Single Power Supplies):**

Item	Symbol	Min	Typ	Max	Unit
Power Supply Voltage	$V_{DD}$	3.00	3.30	3.60	V
Input Voltage	$V_I$	$V_{SS}$	--	$V_{DD}^{*1}$	V
Ambient Temperature	$T_a$	0 -40	25 25	$70^{*2}$ $85^{*3}$	°C
Normal Input for Rising Edge Input	$t_{ri}$	--	--	50	ns
Normal Input for Falling Edge Input	$t_{fi}$	--	--	50	ns
Schmitt Input for Rising Edge Input	$t_{ri}$	--	--	5	ms
Schmitt Input for Falling Edge Input	$t_{fi}$	--	--	5	ms

\*1: Possible to use 5.25 or 5.50V of I/O buffer in the open-drain systems and input buffer in the IDC and IDH systems.

\*2: The ambient temperature range is recommended for  $T_j = 0$  to  $80^\circ\text{C}$

\*3: The ambient temperature range is recommended for  $T_j = -40$  to  $125^\circ\text{C}$

**Recommended Operating Conditions (For Single Power Supplies):**

Item	Symbol	Min	Typ	Max	Unit
Power Supply Voltage	$V_{DD}$	1.80	2.00	2.20	V
Input Voltage	$V_I$	$V_{SS}$	--	$V_{DD}^{*1}$	V
Ambient Temperature	$T_a$	0 -40	25 25	$70^{*2}$ $85^{*3}$	°C
Normal Input for Rising Edge Input	$t_{ri}$	--	--	100	ns
Normal Input for Falling Edge Input	$t_{fi}$	--	--	100	ns
Schmitt Input for Rising Edge Input	$t_{ri}$	--	--	10	ms
Schmitt Input for Falling Edge Input	$t_{fi}$	--	--	10	ms

\*1: Possible to use 5.25 or 5.50V of I/O buffer in the open-drain systems and input buffer in the IDC and IDH systems.

\*2: The ambient temperature range is recommended for  $T_j = 0$  to  $80^\circ\text{C}$

\*3: The ambient temperature range is recommended for  $T_j = -40$  to  $125^\circ\text{C}$

**Recommended Operating Conditions (For Dual Power Supplies):**

Item	Symbol	Min	Typ	Max	Unit
Power Supply Voltage (High Voltage)	HV <sub>DD</sub>	4.75	5.00	5.25	V
		4.50	5.00	5.50	
Power Supply Voltage (Low Voltage)	LV <sub>DD</sub>	3.00	3.30	3.60	V
Input Voltage	HV <sub>I</sub>	V <sub>SS</sub>	--	HV <sub>DD</sub>	V
	LV <sub>I</sub>	V <sub>SS</sub>	--	LV <sub>DD</sub> <sup>*1</sup>	
Ambient Temperature	T <sub>a</sub>	0	25	70 <sup>*2</sup>	°C
		-40	25	85 <sup>*3</sup>	
Normal Input for Rising Edge Input	tri	--	--	50	ns
Normal Input for Falling Edge Input	tri	--	--	50	ns
Schmitt Input for Rising Edge Input	tri	--	--	5	ms
Schmitt Input for Falling Edge Input	tri	--	--	5	ms

\*1: Possible to use 5.25 or 5.50V of I/O buffer in the open-drain systems and input buffer in the LIDC and LIDH systems.

\*2: The ambient temperature range is recommended for T<sub>j</sub> = 0 to 80°C

\*3: The ambient temperature range is recommended for T<sub>j</sub> = -40 to 125°C

**Recommended Operating Conditions (For Dual Power Supplies):**

Item	Symbol	Min	Typ	Max	Unit
Power Supply Voltage (High Voltage)	HV <sub>DD</sub>	3.00	3.30	3.60	V
Power Supply Voltage (Low Voltage)	LV <sub>DD</sub>	1.80	2.00	2.20	V
Input Voltage	HV <sub>I</sub>	V <sub>SS</sub>	--	HV <sub>DD</sub>	V
	LV <sub>I</sub>	V <sub>SS</sub>	--	LV <sub>DD</sub>	
Ambient Temperature	T <sub>a</sub>	0	25	70 <sup>*1</sup>	°C
		-40	25	85 <sup>*2</sup>	
Normal Input for Rising Edge Input	H <sub>tri</sub>	--	--	50	ns
	L <sub>tri</sub>	--	--	100	
Normal Input for Falling Edge Input	H <sub>tfi</sub>	--	--	50	ns
	L <sub>tfi</sub>	--	--	100	
Schmitt Input for Rising Edge Input	H <sub>tri</sub>	--	--	5	ms
	L <sub>tri</sub>	--	--	10	
Schmitt Input for Falling Edge Input	H <sub>tfi</sub>	--	--	5	ms
	L <sub>tfi</sub>	--	--	10	

\*1: Possible to use 5.25 or 5.50V of I/O buffer in the open-drain systems and input buffer in the LIDC and LIDH systems or HIDC and HIDH systems.

\*2: The ambient temperature range is recommended for T<sub>j</sub> = 0 to 80°C

\*3: The ambient temperature range is recommended for T<sub>j</sub> = -40 to 125°C

**Electrical Characteristics of the S1L50000 Series:**

( $V_{DD} = 5.0V$ ,  $V_{SS} = 0V$ ,  $T_a = -40$  to  $85^{\circ}C$ )

Item	Symbol	Conditions	Min	Typ	Max	Unit
Input Leakage Current	$I_{LI}$	--	-1	--	1	$\mu A$
Off State Leakage Current	$I_{OZ}$	--	-1	--	1	$\mu A$
High Level Output Voltage	$V_{OH}$	$I_{OH} = -0.1mA$ (Type S), $-1mA$ (Type M), $-3mA$ (Type 1), $-8mA$ (Type 2), $-12mA$ (Type 3, Type 4) $V_{DD} = \text{Min}$	$HV_{DD}$ -0.4	--	--	V
Low Level Output Voltage	$V_{OL}$	$I_{OL} = 0.1mA$ (Type S), $1mA$ (Type M), $3mA$ (Type 1), $8mA$ (Type 2), $12mA$ (Type 3), $24mA$ (Type 4) $V_{DD} = \text{Min}$	--	--	0.4	V
High Level Input Voltage	$V_{IH1}$	CMOS Level, $HV_{DD} = \text{Max}$	3.5	--	--	V
Low Level Input Voltage	$V_{IL1}$	CMOS Level, $HV_{DD} = \text{Min}$	--	--	1.0	V
High Level Input Voltage	$V_{T1+}$	CMOS Schmitt	2.0	--	4.0	V
Low Level Input Voltage	$V_{T1-}$	CMOS Schmitt	0.8	--	3.1	V
Hysteresis Voltage	$V_{H1}$	CMOS Schmitt	0.3	--	--	V
High Level Input Voltage	$V_{IH2}$	TTL Level, $HV_{DD} = \text{Max}$	2.0	--	--	V
Low Level Input Voltage	$V_{IL2}$	TTL Level, $HV_{DD} = \text{Min}$	--	--	0.8	V
High Level Input Voltage	$V_{T2+}$	TTL Schmitt	1.2	--	2.4	V
Low Level Input Voltage	$V_{T2-}$	TTL Schmitt	0.6	--	1.8	V
Hysteresis Voltage	$V_{H2}$	TTL Schmitt	0.1	--	--	V
High Level Input Voltage	$V_{IH3}$	PCI Level, $HV_{DD} = \text{Max}$	2.0	--	--	V
Low Level Input Voltage	$V_{IL3}$	PCI Level, $HV_{DD} = \text{Min}$	--	--	0.8	V
High Level Output Current	$I_{OH3}$	PCI Response, $V_{OH} = 1.4V$ , $HV_{DD} = \text{Min}$ $V_{OH} = 3.1V$ , $HV_{DD} = \text{Max}$	-44 --	-- --	-- -142	$mA$ $mA$
Low Level Output Current	$I_{OL3}$	PCI Response $V_{OH} = 2.20V$ , $HV_{DD} = \text{Min}$ $V_{OL} = 0.71V$ , $HV_{DD} = \text{Max}$	95 --	-- --	-- 206	$mA$ $mA$
Pull-up Resistance*	$R_{PU}$	$V_I = 0V$	Type 1 Type 2	30 60	60 120	(120) 144 (240) 288 $K\Omega$
Pull-down Resistance*	$R_{PD}$	$V_I = V_{DD}$	Type 1 Type 2	30 60	60 120	(120) 144 (240) 288 $K\Omega$
High Level Maintenance Current	$I_{BHH}$	Bus Hold Response, $V_{IN} = 2.0V$ (TTL) $HV_{DD} = \text{Min}$	--	--	-80	$\mu A$
Low Level Maintenance Current	$I_{BHL}$	Bus Hold Response, $V_{IN} = 0.8V$ (TTL) $HV_{DD} = \text{Min}$	--	--	33	$\mu A$
High Level Reversal Current	$I_{BHHO}$	Bus Hold Response, $V_{IN} = 0.8V$ (TTL) $HV_{DD} = \text{Max}$	-550	--	--	$\mu A$
Low Level Reversal Current	$I_{BHLO}$	Bus Hold Response, $V_{IN} = 2.0V$ (TTL) $HV_{DD} = \text{Max}$	330	--	--	$\mu A$
Input Terminal Capacitance	$C_I$	$f = 1MHz$ , $V_{DD} = 0V$	--	--	10	pF
Output Terminal Capacitance	$C_O$	$f = 1MHz$ , $V_{DD} = 0V$	--	--	10	pF
Input/Output Terminal Capacitance	$C_{IO}$	$f = 1MHz$ , $V_{DD} = 0V$	--	--	10	pF

\* The values in parentheses are for the case of  $T_a = 0$  to  $70^{\circ}C$ .

**Electrical Characteristics of the S1L50000 Series:**

( $V_{DD} = 3.3V \pm 0.3V$ ,  $V_{SS} = 0V$ ,  $T_a = -40$  to  $85^\circ C$ )

Item	Symbol	Conditions	Min	Typ	Max	Unit	
Quiescent Current	$I_{DD5}$	Quiescent Conditions	--	--	170	$\mu A$	
Input Leakage Current	$I_{LI}$	--	-1	--	1	$\mu A$	
Off State Leakage Current	$I_{OZ}$	--	-1	--	1	$\mu A$	
High Level Output Voltage	$V_{OH}$	$I_{OH} = -0.1mA$ (Type S), $-1mA$ (Type M), $-2mA$ (Type 1), $-6mA$ (Type 2), $-12mA$ (Type 3, Type 4) $V_{DD} = \text{Min}$	$V_{DD}$ -0.4	--	--	V	
Low Level Output Voltage	$V_{OL}$	$I_{OL} = 0.1mA$ (Type S), $1mA$ (Type M), $2mA$ (Type 1), $6mA$ (Type 2), $12mA$ (Type 3), $24mA$ (Type 4) $V_{DD} = \text{Min}$	--	--	0.4	V	
High Level Input Voltage	$V_{IH1}$	LVTTL Level, $V_{DD} = \text{Max}$	2.0	--	--	V	
Low Level Input Voltage	$V_{IL1}$	LVTTL Level, $V_{DD} = \text{Min}$	--	--	0.8	V	
High Level Input Voltage	$V_{T1+}$	LVTTL Schmitt	1.1	--	2.4	V	
Low Level Input Voltage	$V_{T1-}$	LVTTL Schmitt	0.6	--	1.8	V	
Hysteresis Voltage	$V_{H1}$	LVTTL Schmitt	0.1	--	--	V	
High Level Input Voltage	$V_{IH3}$	PCI Level, $V_{DD} = \text{Max}$	1.71	--	--	V	
Low Level Input Voltage	$V_{IL3}$	PCI Level, $V_{DD} = \text{Min}$	--	--	0.98	V	
High Level Output Current	$I_{OH3}$	PCI Response, $V_{OH} = 0.90V$ , $V_{DD} = \text{Min}$ $V_{OH} = 2.52V$ , $V_{DD} = \text{Max}$	-36 --	-- --	-- -115	$mA$ $mA$	
Low Level Output Current	$I_{OL3}$	PCI Response $V_{OH} = 1.80V$ , $V_{DD} = \text{Min}$ $V_{OL} = 2.52V$ , $V_{DD} = \text{Max}$	48 --	-- --	-- 137	$mA$ $mA$	
Pull-up Resistance**	$R_{PU}$	$V_I = 0V$	Type 1	20	50	(100) 120	$K\Omega$
			Type 2	40	100	(200) 240	
Pull-down Resistance**	$R_{PD}$	$V_I = V_{DD}$	Type 1	20	50	(100) 120	$K\Omega$
			Type 2	40	100	(200) 240	
High Level Maintenance Current	$I_{BHH}$	Bus Hold Response, $V_{IN} = 2.0V$ , $V_{DD} = \text{Min}$	--	--	-20	$\mu A$	
Low Level Maintenance Current	$I_{BHL}$	Bus Hold Response, $V_{IN} = 0.8V$ , $V_{DD} = \text{Min}$	--	--	17	$\mu A$	
High Level Reversal Current	$I_{BHHO}$	Bus Hold Response, $V_{IN} = 0.8V$ , $V_{DD} = \text{Max}$	-350	--	--	$\mu A$	
Low Level Reversal Current	$I_{BHLO}$	Bus Hold Response, $V_{IN} = 2.0V$ , $V_{DD} = \text{Max}$	210	--	--	$\mu A$	
Input Terminal Capacitance	$C_I$	$f = 1MHz$ , $V_{DD} = 0V$	--	--	10	pF	
Output Terminal Capacitance	$C_O$	$f = 1MHz$ , $V_{DD} = 0V$	--	--	10	pF	
Input/Output Terminal Capacitance	$C_{IO}$	$f = 1MHz$ , $V_{DD} = 0V$	--	--	10	pF	

\* The quiescent current is a typical value ( $T_j=85^\circ C$ ) for each master.

\*\* The values in parentheses are for the case of  $T_a = 0$  to  $70^\circ C$ .

**Electrical Characteristics of the S1L50000 Series:**

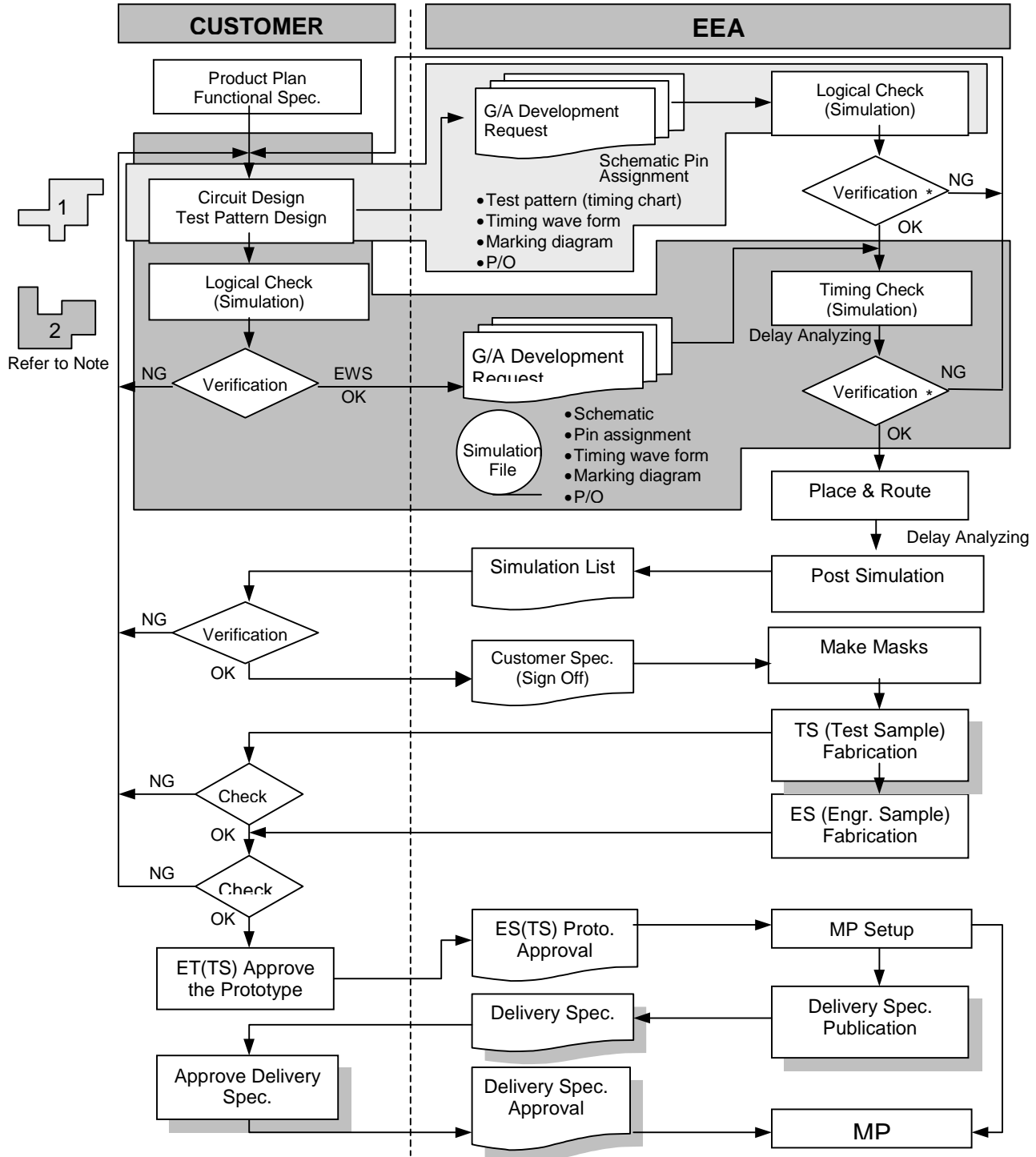
( $V_{DD} = 2.0V \pm 0.2V$ ,  $V_{SS} = 0V$ ,  $T_a = -40$  to  $85^\circ C$ )

Item	Symbol	Conditions	Min	Typ	Max	Unit	
Quiescent Current	$I_{DDs}$	Quiescent Conditions	--	--	150	$\mu A$	
Input Leakage Current	$I_{LI}$	--	-1	--	1	$\mu A$	
Off State Leakage Current	$I_{OZ}$	--	-1	--	1	$\mu A$	
High Level Output Voltage	$V_{OH}$	$I_{OH} = -0.05mA$ (Type S), $-0.3mA$ (Type M), $-0.6mA$ (Type 1), $-2mA$ (Type 2), $-4mA$ (Type 3, Type 4) $V_{DD} = \text{Min}$	$V_{DD}$ -0.2	--	--	V	
Low Level Output Voltage	$V_{OL}$	$I_{OL} = 0.05mA$ (Type S), $0.3mA$ (Type M), $0.6mA$ (Type 1), $2mA$ (Type 2), $4mA$ (Type 3), $8mA$ (Type 4) $V_{DD} = \text{Min}$	--	--	0.2	V	
High Level Input Voltage	$V_{IH1}$	CMOS Level, $V_{DD} = \text{Max}$	1.6	--	--	V	
Low Level Input Voltage	$V_{IL1}$	CMOS Level, $V_{DD} = \text{Min}$	--	--	0.3	V	
High Level Input Voltage	$V_{T1+}$	CMOS Schmitt	0.4	--	1.6	V	
Low Level Input Voltage	$V_{T1-}$	CMOS Schmitt	0.3	--	1.4	V	
Hysteresis Voltage	$V_{H1}$	CMOS Schmitt	0	--	--	V	
Pull-up Resistance	$R_{PU}$	$V_I = 0V$	Type 1	30	120	300	$K\Omega$
			Type 2	60	240	600	
Pull-down Resistance	$R_{PD}$	$V_I = V_{DD}$	Type 1	30	120	300	$K\Omega$
			Type 2	60	240	600	
High Level Maintenance Current	$I_{BHH}$	Bus Hold Response, $V_{IN} = 1.6V$ , $V_{DD} = \text{Min}$	--	--	-2	$\mu A$	
Low Level Maintenance Current	$I_{BHL}$	Bus Hold Response, $V_{IN} = 0.3V$ , $V_{DD} = \text{Min}$	--	--	2	$\mu A$	
High Level Reversal Current	$I_{BHHO}$	Bus Hold Response, $V_{IN} = 0.3V$ , $V_{DD} = \text{Max}$	-100	--	--	$\mu A$	
Low Level Reversal Current	$I_{BHLO}$	Bus Hold Response, $V_{IN} = 1.6V$ , $V_{DD} = \text{Max}$	100	--	--	$\mu A$	
Input Terminal Capacitance	$C_I$	$f = 1MHz$ , $V_{DD} = 0V$	--	--	10	pF	
Output Terminal Capacitance	$C_O$	$f = 1MHz$ , $V_{DD} = 0V$	--	--	10	pF	
Input/Output Terminal Capacitance	$C_{IO}$	$f = 1MHz$ , $V_{DD} = 0V$	--	--	10	pF	

\* The quiescent current is a typical value ( $T_j=85^\circ C$ ) for each master.



GATE ARRAY DEVELOPMENT FLOW



\* Jobs are done by customer and EEA engineer. Steps in shadowed boxes are based on customer's requirement.

NOTE: When the customer performs all tasks to the point of logical simulations and delay simulations on engineering workstations, etc., the route taken is (2, Joint Design). When EEA performs the logical simulations, the route taken is (1, Turnkey Design).

## ■ EEA CUSTOMER ENGINEERING

To help customers implement their design of EEA ASIC's, we offer training at our design centers and at customer sites when required.

When a design is started, an EEA engineer is assigned to the project and will remain with the project through its completion. EEA engineers will work with the customer on design, software and other technical issues. When the design files are transferred to EEA, the assigned engineer will verify the design's integrity and prepare it for place and route. The EEA Customer Engineering Group provides all technical customer-support services including:

- Pre-Sale Technical Support
- Customer Training
- Design Assistance
- Custom Cell Development
- Place and Route
- Scan Insertion and ATPG
- Netlist Conversion and Synthesis
- Software Documentation
- Simulation Support
- Turnkey Design
- Design Verification
- Static Timing Analysis
- JTAG Insertion
- Test Vector Conversion

## ■ EDA/CAE SUPPORT

- Schematic Capture
  - Viewlogic (Synopsys): Viewdraw
  - EEA: Auklet (ECS)
- Synthesis
  - Synopsys: DesignCompiler
  - Exemplar Logic: Leonardo
- Simulation
  - Cadence: Verilog-XL
  - Synopsys: VSS (VHDL)
  - Avant!: Polaris (Purespeed)
  - Viewlogic (Synopsys): Viewsim
  - Modeltech: V-System (VHDL)
- DFT
  - Synopsys: TestCompiler+
  - Viewlogic (Synopsys): TestGen (Sunrise)
- Place & Route
  - Cadence: GateEnsemble
  - Avant!: Aquarius-GA (Apollo)
- Delay Calculation (Post-Route)
  - EEA: Peacock (EXDT)

■ **EDA/CAE SUPPORT (continued)**

- Static Timing
  - Synopsys: PrimeTime (DesignTime)
  - Viewlogic (Synopsys): Motive
- Layout Verification
  - Cadence: Dracula/LVS

**NOTICE**

No part of this material may be reproduced or duplicated in any form or by any means without the written permission of EPSON ELECTRONICS AMERICA, INC.. EEA reserves the right to make changes to this material without notice. EEA does not assume any liability of any kind arising out of any inaccuracies contained in this material or due to its application or use in any product or circuit and, further, there is no representation that this material is applicable to products requiring high level reliability, such as, medical products. Moreover, no license to any intellectual property rights is granted by implication or otherwise, and there is no representation or warranty that anything made in accordance with this material will be free from any patent or copyright infringement of a third party. This material or portions thereof may contain technology or the subject relating to strategic products under the control of the Foreign Exchange and Foreign Trade Control Law of Japan and may require an export license from the Ministry of International Trade and Industry or other approval from another government agency.

EPSON implies SEIKO EPSON CORPORATION and EPSON affiliated company.

© EPSON ELECTRONICS AMERICA, INC. 1999 All Rights Reserved, Rev. 2.3

**Trademark & Company Name**

XNF is registered trademark of Synopsys Inc. All other product names mentioned herein are trademarks and/or registered trademarks of their respective owners.

For additional information about EEA ASIC products and services, or to discuss a solution tailored to your specific requirements, call your local EEA sales office or contact the factory.

**Northwest Regional  
Sales Office & Design Center**

150 River Oaks Parkway  
San Jose, CA 95134  
Phone: (408) 922-0200  
Fax: (408) 922-0238

**Northeast Regional  
Sales Office & Design Center**

301 Edgewater Place, Suite 120  
Wakefield, MA 01880  
Phone: (781) 246-3600  
Fax: (781) 246-5443

**Southeast Regional  
Sales Office**

4300 Six Forks Road, Suite 430,  
Raleigh, NC 27609  
Phone: (919) 781-7667  
Fax: (919) 781-6778

**Central Regional  
Sales Office**

1450 E. American Lane, Suite 1550  
Schaumburg, IL 60173  
Phone: (847) 517-7667  
Fax: (847) 517-7601

<http://www.eea.epson.com>